



SOT1348-1

plastic, thermal enhanced extremely thin small outline
package; no leads; 6 terminals; body 2.0 x 2.0 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON6
Package type industry code	HXSON6
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-5-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	6	-	



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2. Package outline

HXSON6: plastic, thermal enhanced extremely thin small outline package; no leads; 6 terminals; body 2.0 x 2.0 x 0.5 mm

SOT1348-1

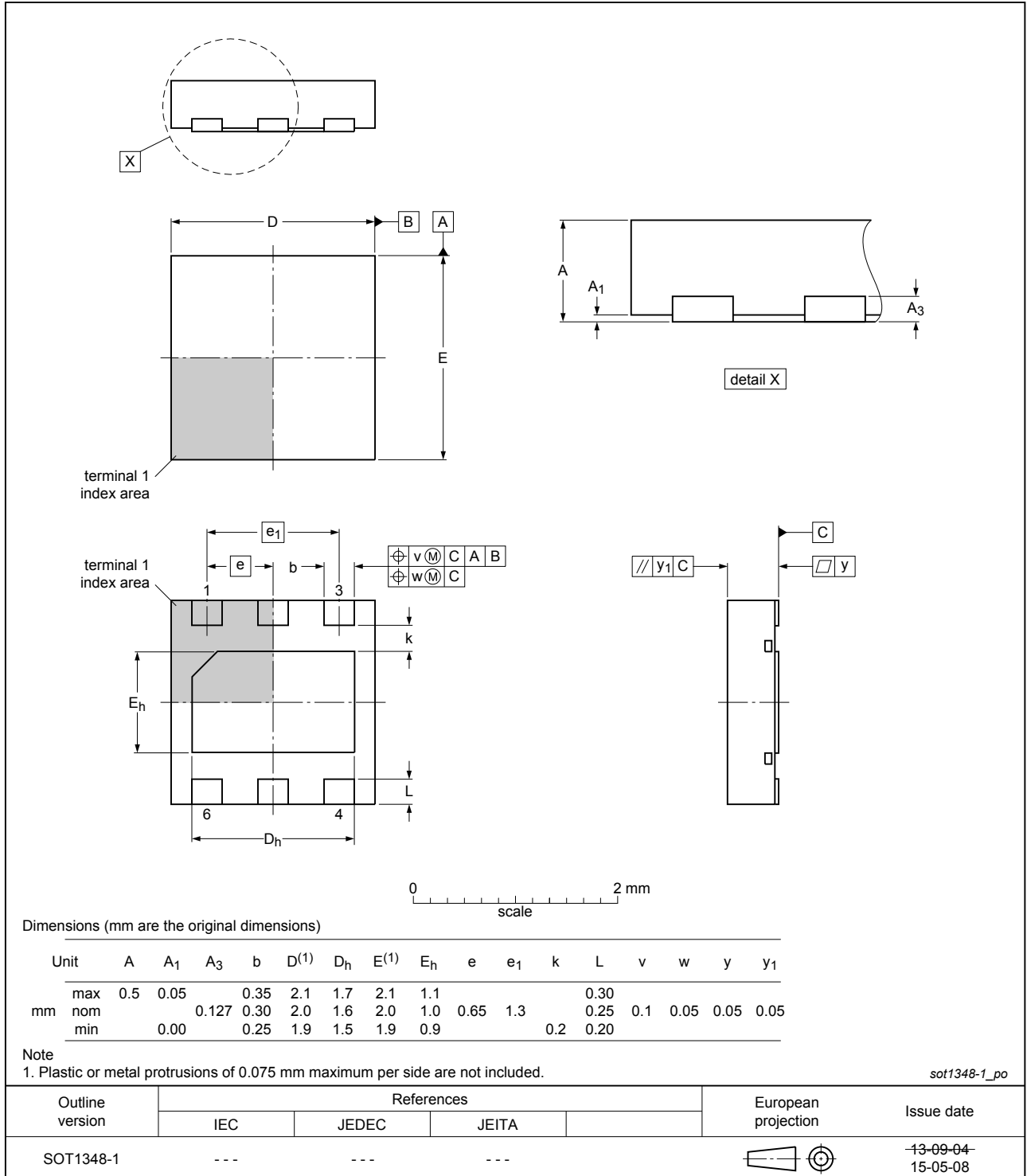
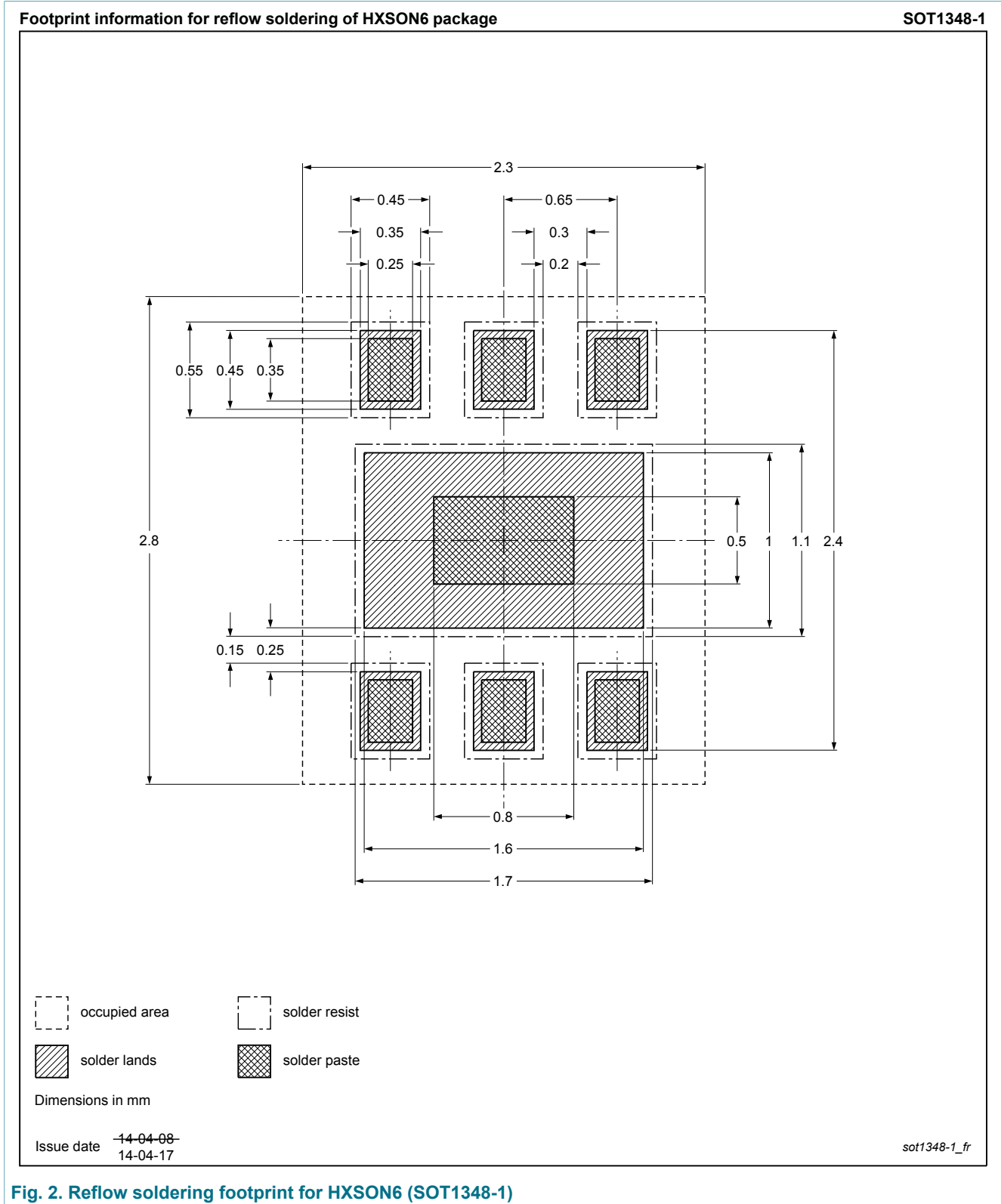


Fig. 1. Package outline HXSON6 (SOT1348-1)

plastic, thermal enhanced extremely thin small
outline package; no leads; 6 terminals; body 2.0
x 2.0 x 0.5 mm

3. Soldering



plastic, thermal enhanced extremely thin small
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x 2.0 x 0.5 mm

4. Legal information

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